

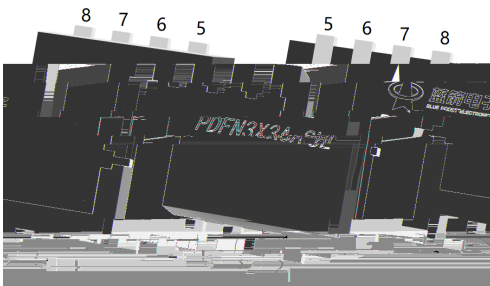
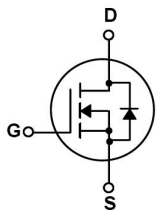
Rev.B Oct.-2024

G; =E *2 *8\$/C E D F J

N-Channel Enhancement Mode Field Effect Transistor in a PDFN3² 3A-8L Plastic Package.

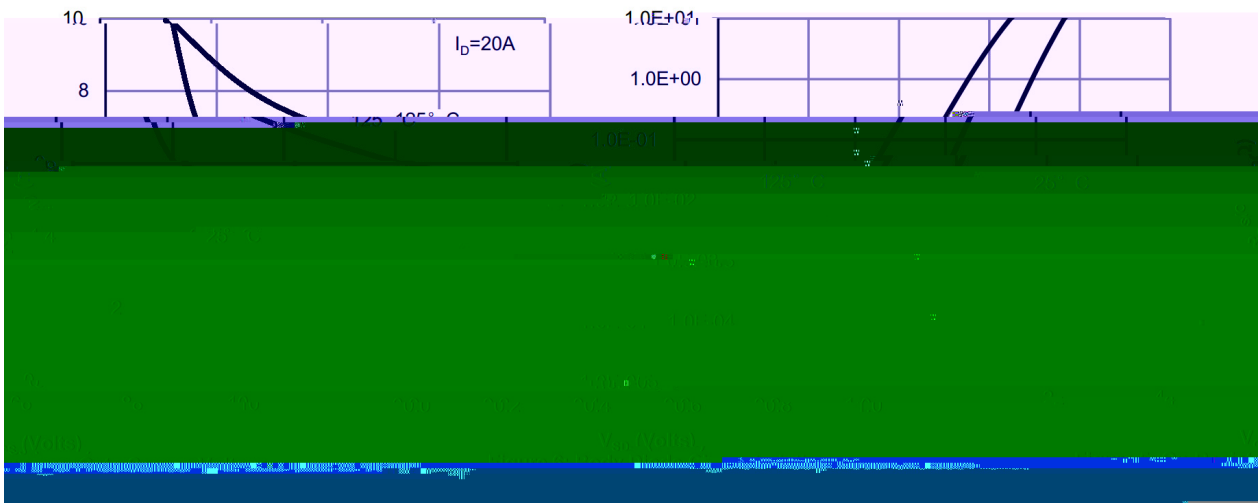
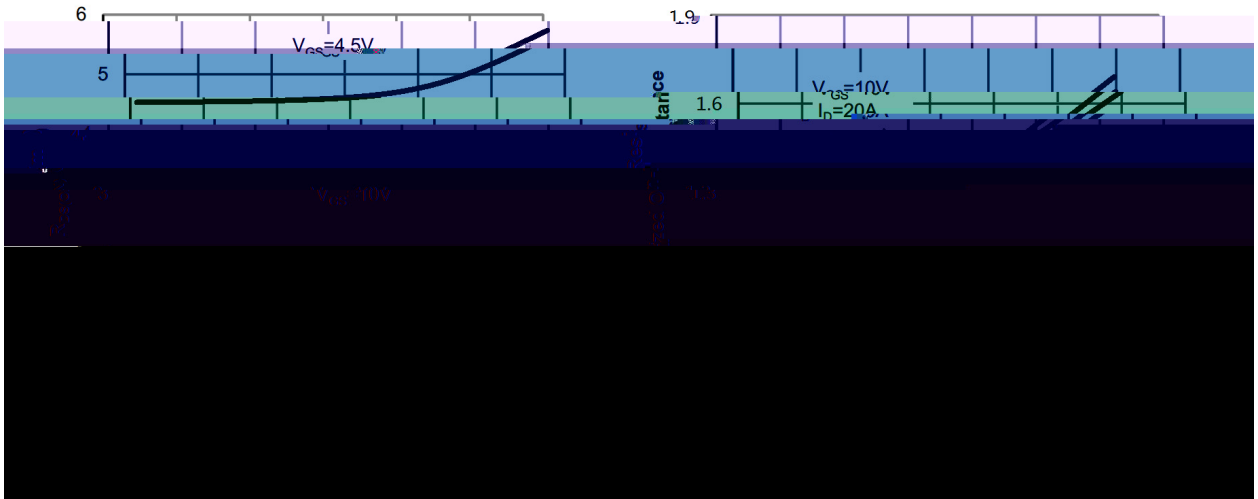
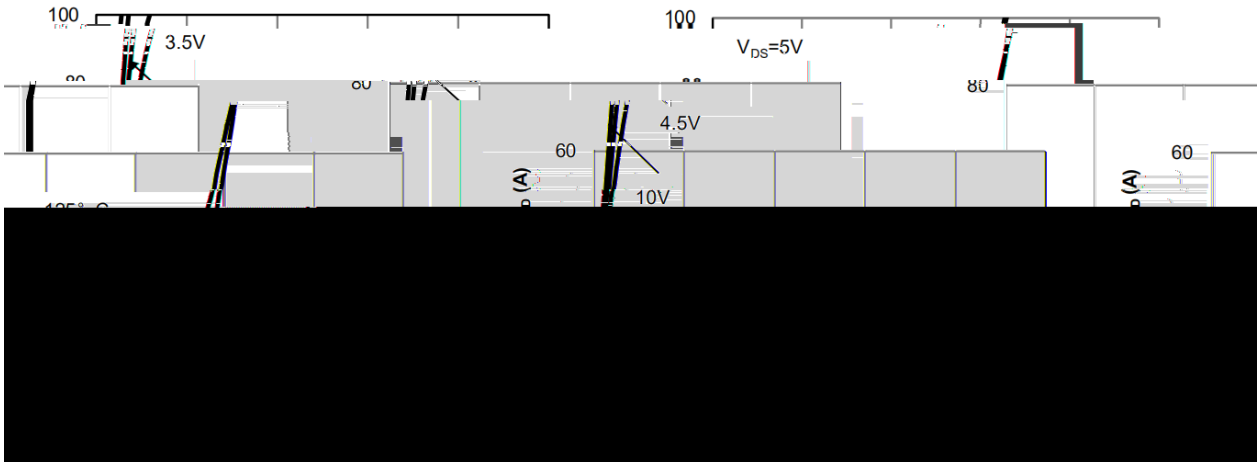
$V_{DS} (V) = 30V$ $I_D = 76A (V_{GS} = \pm 20V)$
 $R_{DS(ON)} @ 10V \quad 3.5m$ (Typ.3.3m)
 $R_{DS(ON)} @ 4.5V \quad 6.5m$ (Typ.4.7m)
 HF Product.

Load Switch Applications, Battery Power Management.

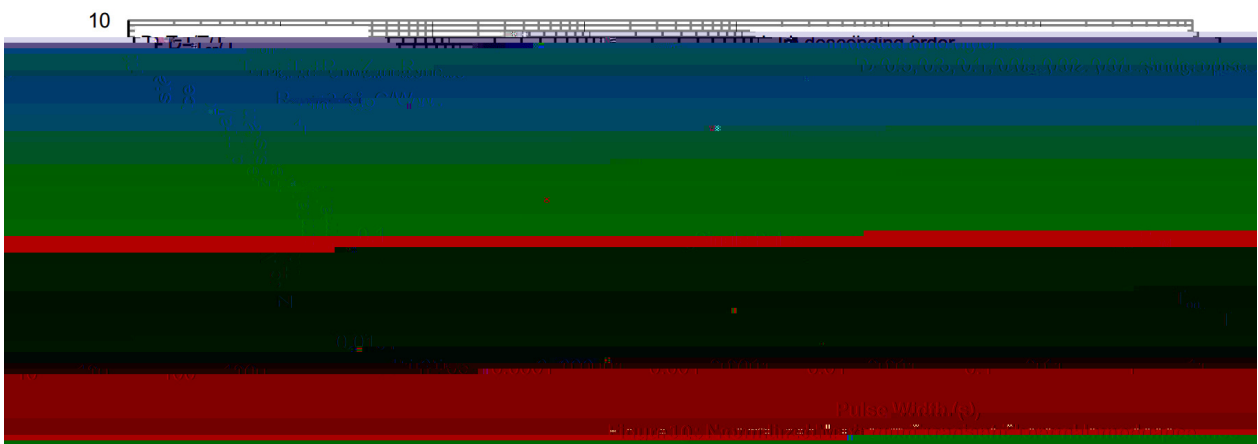
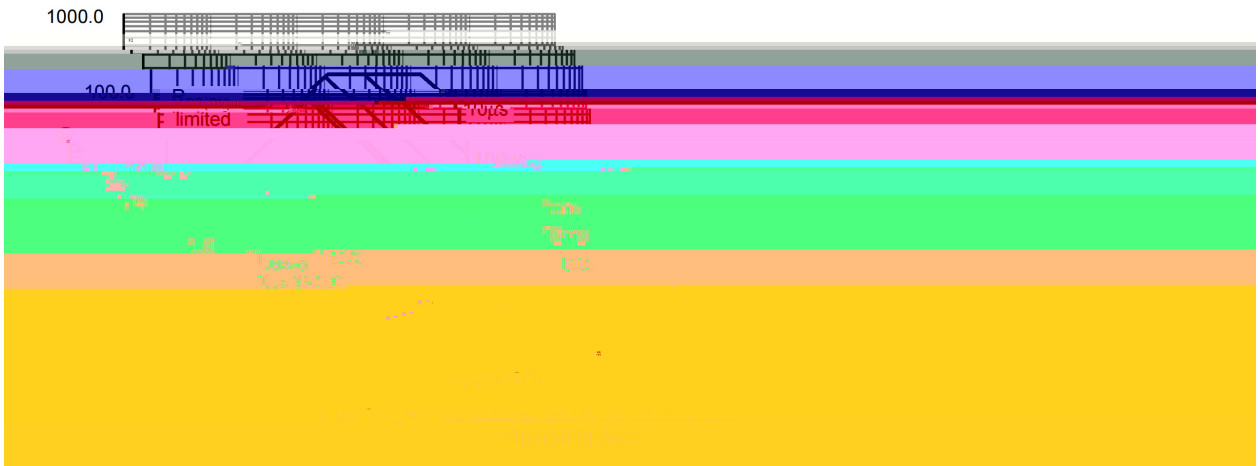
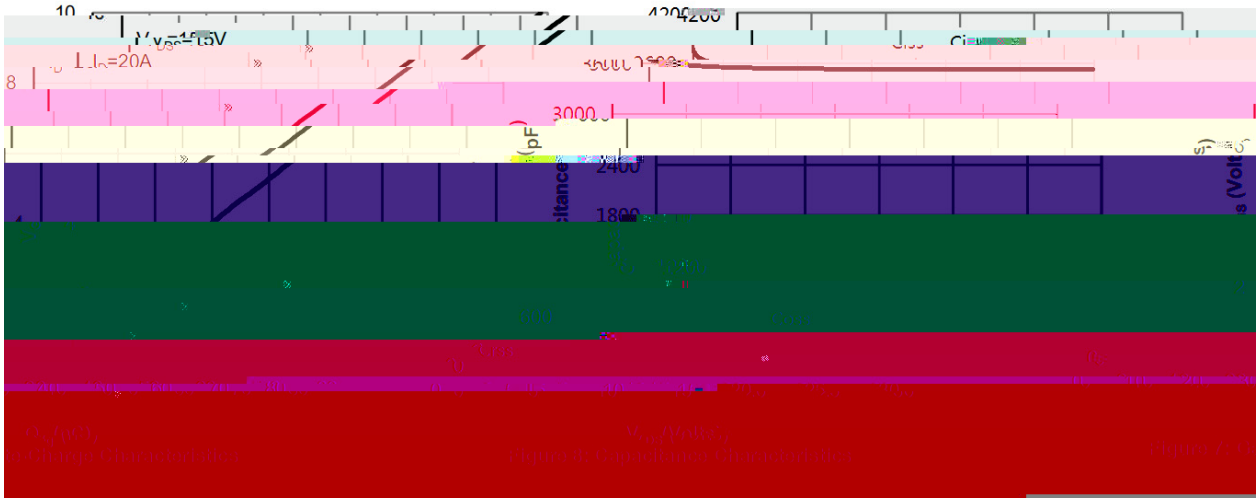


Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	30	V
Drain Current		$I_D(T_C=25^\circ\text{C})$	76	A
Drain Current - Pulsed		I_{DM}	190	A
Gate-Source Voltage		V_{GSS}	± 20	V
Single Pulsed Avalanche Energy		E_{AS}	449	mJ
Avalanche Current		I_{AS}	33.5	A
Power Dissipation		$P_D(T_C=25^\circ\text{C})$	35	W
Operating and Storage Temperature Range		T_J, T_{stg}	-55 to 150	
Junction-to-Ambient	$t = 10$	R_{JA}	42	/W
Junction-to-Ambient	Steady-State		78	
Junction-to-Case	Steady-State	R_{JC}	3.6	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	30	35		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V$ $V_{GS}=0V$			1	μA
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 20V$ $V_{DS}=0V$			± 0.1	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V$ $I_D=20A$		3.3	3.5	m
		$V_{GS}=4.5V$ $I_D=10A$		4.7	6.5	m
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_S=1A$			1.2	V
Input Capacitance	C_{iss}	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$		3470		pF
Output Capacitance	C_{oss}			270		
Reverse Transfer Capacitance	C_{rss}			240		
Gate resistance	R_g	V_{GS}				

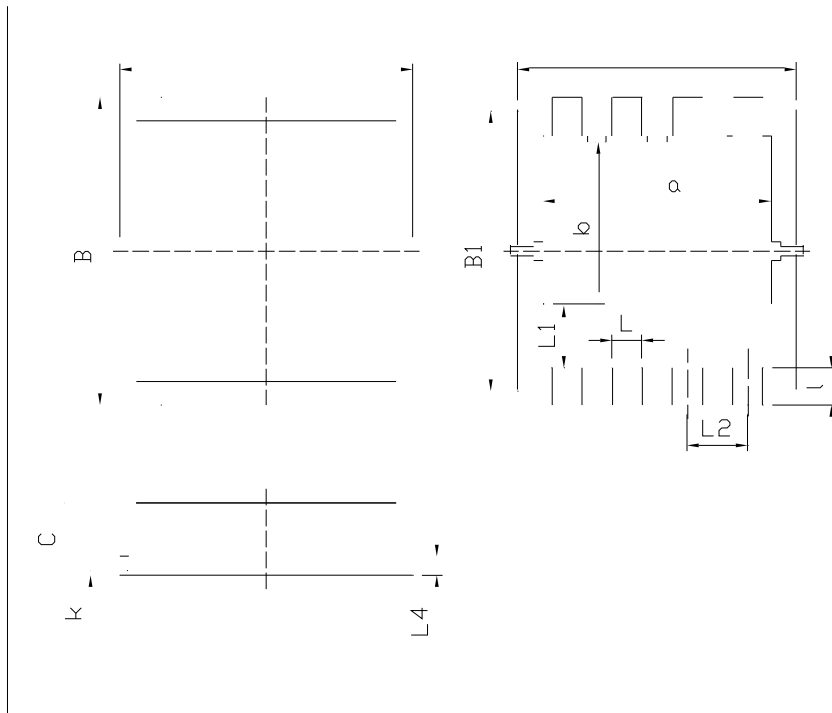


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PDFN3X3A-8L

Unit:mm



C	0.75	0.80	0.85
L	0.25	0.30	0.35
L1	-	-	0.75
L2	0.55	0.65	0.75
L4	0.14	0.15	0.20
a	2.35	2.45	2.55
b	1.635	1.735	1.835
k	0.00	-	0.05
l	0.30	0.40	0.50



BR

035N03

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Note:

BR: Company Code

035N03: Product Type Code

****: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|---------|------------|---|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245..5 | 5..0.5sec; | 2.Peak Temp.:245..5 , Duration:5..0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

260..5	10..1 sec.	Temp.:260±5	Time:10±1 sec
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